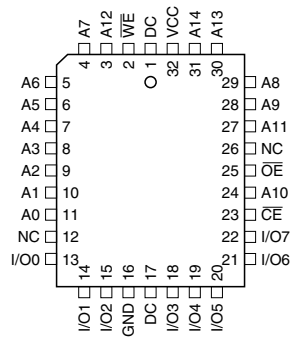


## 2. Pin Configurations

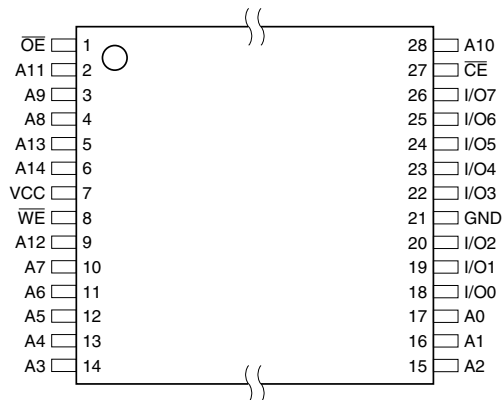
| Pin Name        | Function            |
|-----------------|---------------------|
| A0 - A14        | Addresses           |
| $\overline{CE}$ | Chip Enable         |
| $\overline{OE}$ | Output Enable       |
| $\overline{WE}$ | Write Enable        |
| I/O0 - I/O7     | Data Inputs/Outputs |
| NC              | No Connect          |
| DC              | Don't Connect       |

### 2.1 PLCC and LCC Top View

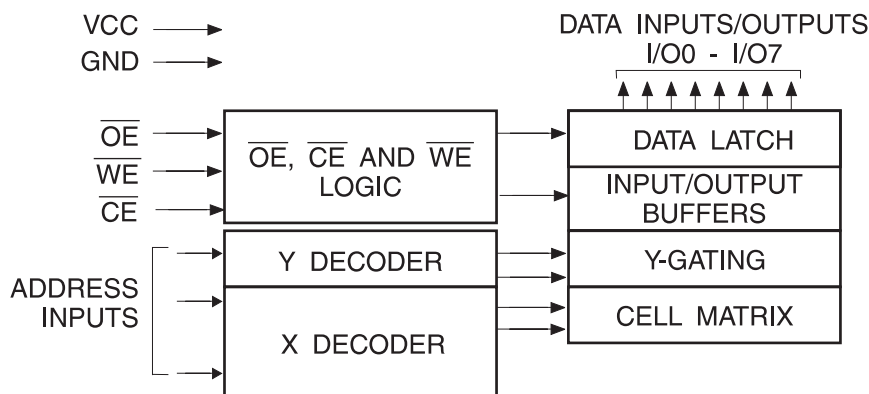


Note: 1. PLCC package pins 1 and 17 are DON'T CONNECT.

### 2.2 TSOP Top View Type 1



### 3. Block Diagram



### 4. Device Operation

#### 4.1 Read

The AT29C256 is accessed like a static RAM. When  $\overline{CE}$  and  $\overline{OE}$  are low and  $\overline{WE}$  is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever  $\overline{CE}$  or  $\overline{OE}$  is high. This dual-line control gives designers flexibility in preventing bus contention.

#### 4.2 Byte Load

A byte load is performed by applying a low pulse on the  $\overline{WE}$  or  $\overline{CE}$  input with  $\overline{CE}$  or  $\overline{WE}$  low (respectively) and  $\overline{OE}$  high. The address is latched on the falling edge of  $\overline{CE}$  or  $\overline{WE}$ , whichever occurs last. The data is latched by the first rising edge of  $\overline{CE}$  or  $\overline{WE}$ . Byte loads are used to enter the 64 bytes of a page to be programmed or the software codes for data protection and chip erasure.

#### 4.3 Program

The device is reprogrammed on a page basis. If a byte of data within a page is to be changed, data for the entire page must be loaded into the device. Any byte that is not loaded during the programming of its page will be indeterminate. Once the bytes of a page are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high-to-low transition on  $\overline{WE}$  (or  $\overline{CE}$ ) within 150  $\mu$ s of the low-to-high transition of  $\overline{WE}$  (or  $\overline{CE}$ ) of the preceding byte. If a high-to-low transition is not detected within 150  $\mu$ s of the last low-to-high transition, the load period will end and the internal programming period will start. A6 to A14 specify the page address. The page address must be valid during each high-to-low transition of  $\overline{WE}$  (or  $\overline{CE}$ ). A0 to A5 specify the byte address within the page. The bytes may be loaded in any order; sequential loading is not required. Once a programming operation has been initiated, and for the duration of  $t_{WC}$ , a read operation will effectively be a polling operation.

## 4.4 Software Data Protection

A software controlled data protection feature is available on the AT29C256. Once the software protection is enabled a software algorithm must be issued to the device before a program may be performed. The software protection feature may be enabled or disabled by the user; when shipped from Atmel®, the software data protection feature is disabled. To enable the software data protection, a series of three program commands to specific addresses with specific data must be performed. After the software data protection is enabled the same three program commands must begin each program cycle in order for the programs to occur. All software program commands must obey the page program timing specifications. Once set, the software data protection feature remains active unless its disable command is issued. Power transitions will not reset the software data protection feature; however, the software feature will guard against inadvertent program cycles during power transitions.

Once set, software data protection will remain active unless the disable command sequence is issued.

After setting SDP, any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of  $t_{WC}$ , a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the  $\overline{WE}$  or  $\overline{CE}$  input with  $\overline{CE}$  or  $\overline{WE}$  low (respectively) and  $\overline{OE}$  high. The address is latched on the falling edge of  $\overline{CE}$  or  $\overline{WE}$ , whichever occurs last. The data is latched by the first rising edge of  $\overline{CE}$  or  $\overline{WE}$ . The 64 bytes of data must be loaded into each sector by the same procedure as outlined in the program section under device operation.

## 4.5 Hardware Data Protection

Hardware features protect against inadvertent programs to the AT29C256 in the following ways: (a)  $V_{CC}$  sense – if  $V_{CC}$  is below 3.8V (typical), the program function is inhibited; (b)  $V_{CC}$  power on delay – once  $V_{CC}$  has reached the  $V_{CC}$  sense level, the device will automatically time out 5 ms (typical) before programming; (c) Program inhibit – holding any one of  $\overline{OE}$  low,  $\overline{CE}$  high or  $\overline{WE}$  high inhibits program cycles; and (d) Noise filter – pulses of less than 15 ns (typical) on the  $\overline{WE}$  or  $\overline{CE}$  inputs will not initiate a program cycle.

## 4.6 Product Identification

The product identification mode identifies the device and manufacturer and may be accessed by a hardware operation. For details, see Operating Modes or Product Identification.

## 4.7 Data Polling

The AT29C256 features  $\overline{DATA}$  polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin.  $\overline{DATA}$  polling may begin at any time during the program cycle.

## 4.8 Toggle Bit

In addition to  $\overline{DATA}$  polling the AT29C256 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

## 4.9 Optional Chip Erase Mode

The entire device can be erased by using a six-byte software code. Please see Software Chip Erase application note for details.

## 5. Absolute Maximum Ratings\*

|                                                                        |                          |
|------------------------------------------------------------------------|--------------------------|
| Temperature Under Bias.....                                            | -55° C to +125° C        |
| Storage Temperature .....                                              | -65° C to +150° C        |
| All Input Voltages (including NC Pins)<br>with Respect to Ground ..... | -0.6V to +6.25V          |
| All Output Voltages<br>with Respect to Ground .....                    | -0.6V to $V_{CC} + 0.6V$ |
| Voltage on $\overline{OE}$<br>with Respect to Ground .....             | -0.6V to +13.5V          |

**\*NOTICE:** Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## 6. DC and AC Operating Range

|                              |      | AT29C256-70  | AT29C256-90  | AT29C256-12  | AT29C256-15  |
|------------------------------|------|--------------|--------------|--------------|--------------|
| Operating Temperature (Case) | Com. | 0°C - 70°C   | 0°C - 70°C   | 0°C - 70°C   | 0°C - 70°C   |
|                              | Ind. | -40°C - 85°C | -40°C - 85°C | -40°C - 85°C | -40°C - 85°C |
| V <sub>CC</sub> Power Supply |      | 5V ± 5%      | 5V ± 10%     | 5V ± 10%     | 5V ± 10%     |

Note:   Not recommended for New Designs.

## 7. Operating Modes

| Mode                    | $\overline{CE}$ | $\overline{OE}$               | $\overline{WE}$ | Ai                                                                    | I/O                              |
|-------------------------|-----------------|-------------------------------|-----------------|-----------------------------------------------------------------------|----------------------------------|
| Read                    | V <sub>IL</sub> | V <sub>IL</sub>               | V <sub>IH</sub> | Ai                                                                    | D <sub>OUT</sub>                 |
| Program <sup>(2)</sup>  | V <sub>IL</sub> | V <sub>IH</sub>               | V <sub>IL</sub> | Ai                                                                    | D <sub>IN</sub>                  |
| 5V Chip Erase           | V <sub>IL</sub> | V <sub>IH</sub>               | V <sub>IL</sub> | Ai                                                                    |                                  |
| Standby/Write Inhibit   | V <sub>IH</sub> | X <sup>(1)</sup>              | X               | X                                                                     | High Z                           |
| Write Inhibit           | X               | X                             | V <sub>IH</sub> |                                                                       |                                  |
| Write Inhibit           | X               | V <sub>IL</sub>               | X               |                                                                       |                                  |
| Output Disable          | X               | V <sub>IH</sub>               | X               |                                                                       | High Z                           |
| High Voltage Chip Erase | V <sub>IL</sub> | V <sub>H</sub> <sup>(3)</sup> | V <sub>IL</sub> | X                                                                     | High Z                           |
| Product Identification  |                 |                               |                 |                                                                       |                                  |
| Hardware                | V <sub>IL</sub> | V <sub>IL</sub>               | V <sub>IH</sub> | A1-A14 = V <sub>IL</sub> , A9 = V <sub>H</sub> , A0 = V <sub>IL</sub> | Manufacturer Code <sup>(4)</sup> |
|                         |                 |                               |                 | A1-A14 = V <sub>IL</sub> , A9 = V <sub>H</sub> , A0 = V <sub>IH</sub> | Device Code <sup>(4)</sup>       |
| Software <sup>(5)</sup> |                 |                               |                 | A0 = V <sub>IL</sub>                                                  | Manufacturer Code <sup>(4)</sup> |
|                         |                 |                               |                 | A0 = V <sub>IH</sub>                                                  | Device Code <sup>(4)</sup>       |

- Notes:
1. X can be V<sub>IL</sub> or V<sub>IH</sub>.
  2. Refer to AC Programming Waveforms.
  3. V<sub>H</sub> = 12.0V ± 0.5V.
  4. Manufacturer Code: 1F, Device Code: DC.
  5. See details under Software Product Identification Entry/Exit.

## 8. DC Characteristics

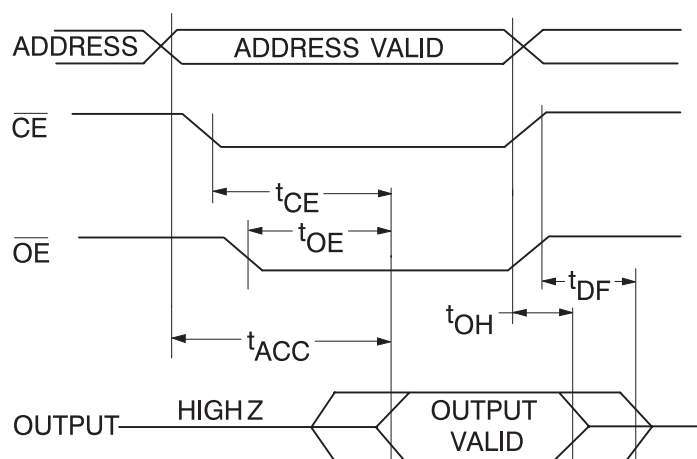
| Symbol           | Parameter                            | Condition                                          | Min | Max  | Units |
|------------------|--------------------------------------|----------------------------------------------------|-----|------|-------|
| I <sub>LI</sub>  | Input Load Current                   | V <sub>IN</sub> = 0V to V <sub>CC</sub>            |     | 10   | μA    |
| I <sub>LO</sub>  | Output Leakage Current               | V <sub>I/O</sub> = 0V to V <sub>CC</sub>           |     | 10   | μA    |
| I <sub>SB1</sub> | V <sub>CC</sub> Standby Current CMOS | $\overline{CE} = V_{CC} - 0.3V$ to V <sub>CC</sub> |     | 300  | μA    |
| I <sub>SB2</sub> | V <sub>CC</sub> Standby Current TTL  | $\overline{CE} = 2.0V$ to V <sub>CC</sub>          |     | 3    | mA    |
| I <sub>CC</sub>  | V <sub>CC</sub> Active Current       | f = 5 MHz; I <sub>OUT</sub> = 0 mA                 |     | 50   | mA    |
| V <sub>IL</sub>  | Input Low Voltage                    |                                                    |     | 0.8  | V     |
| V <sub>IH</sub>  | Input High Voltage                   |                                                    | 2.0 |      | V     |
| V <sub>OL</sub>  | Output Low Voltage                   | I <sub>OL</sub> = 2.1 mA                           |     | 0.45 | V     |
| V <sub>OH1</sub> | Output High Voltage                  | I <sub>OH</sub> = -400 μA                          | 2.4 |      | V     |
| V <sub>OH2</sub> | Output High Voltage CMOS             | I <sub>OH</sub> = -100 μA; V <sub>CC</sub> = 4.5V  | 4.2 |      | V     |

## 9. AC Read Characteristics

| Symbol            | Parameter                                                                               | AT29C256-70 |     | AT29C256-90 |     | AT29C256-12 |     | AT29C256-15 |     | Units |
|-------------------|-----------------------------------------------------------------------------------------|-------------|-----|-------------|-----|-------------|-----|-------------|-----|-------|
|                   |                                                                                         | Min         | Max | Min         | Max | Min         | Max | Min         | Max |       |
| $t_{ACC}$         | Address to Output Delay                                                                 |             | 70  |             | 90  |             | 120 |             | 150 | ns    |
| $t_{CE}^{(1)}$    | $\overline{CE}$ to Output Delay                                                         |             | 70  |             | 90  |             | 120 |             | 150 | ns    |
| $t_{OE}^{(2)}$    | $\overline{OE}$ to Output Delay                                                         | 0           | 40  | 0           | 40  | 0           | 50  | 0           | 70  | ns    |
| $t_{DF}^{(3)(4)}$ | $\overline{CE}$ or $\overline{OE}$ to Output Float                                      | 0           | 25  | 0           | 25  | 0           | 30  | 0           | 40  | ns    |
| $t_{OH}$          | Output Hold from $\overline{OE}$ , $\overline{CE}$ or Address, whichever occurred first | 0           |     | 0           |     | 0           |     | 0           |     | ns    |

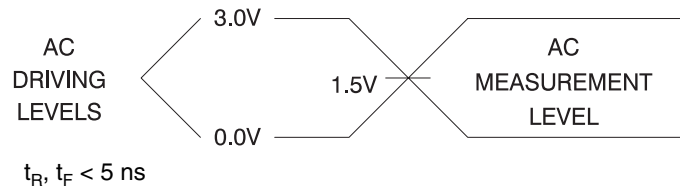
Note:  Not recommended for New Designs.

## 10. AC Read Waveforms<sup>(1)(2)(3)(4)</sup>

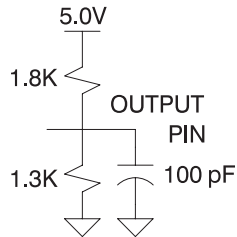


- Notes:
- $\overline{CE}$  may be delayed up to  $t_{ACC} - t_{CE}$  after the address transition without impact on  $t_{ACC}$ .
  - $\overline{OE}$  may be delayed up to  $t_{CE} - t_{OE}$  after the falling edge of  $\overline{CE}$  without impact on  $t_{CE}$  or by  $t_{ACC} - t_{OE}$  after an address change without impact on  $t_{ACC}$ .
  - $t_{DF}$  is specified from  $\overline{OE}$  or  $\overline{CE}$  whichever occurs first (CL = 5 pF).
  - This parameter is characterized and is not 100% tested.

## 11. Input Test Waveforms and Measurement Level



## 12. Output Test Load



## 13. Pin Capacitance

$f = 1 \text{ MHz}$ ,  $T = 25^\circ\text{C}^{(1)}$

| Symbol    | Typ | Max | Units | Conditions     |
|-----------|-----|-----|-------|----------------|
| $C_{IN}$  | 4   | 6   | pF    | $V_{IN} = 0V$  |
| $C_{OUT}$ | 8   | 12  | pF    | $V_{OUT} = 0V$ |

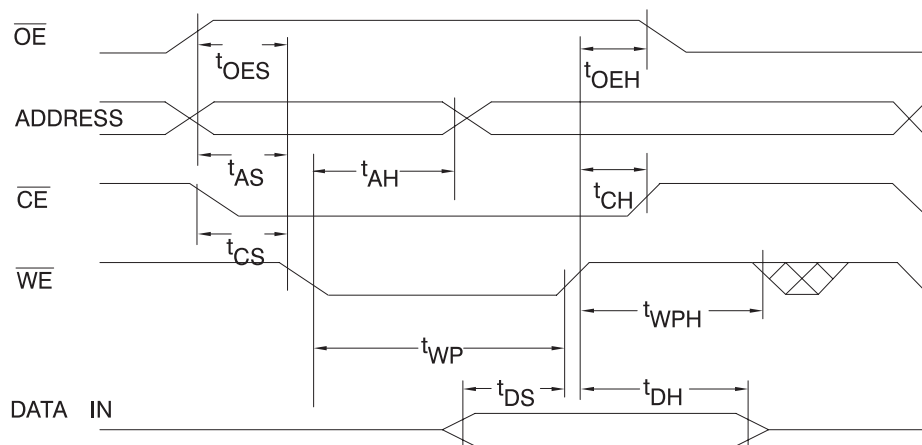
Note: 1. This parameter is characterized and is not 100% tested.

## 14. AC Byte Load Characteristics

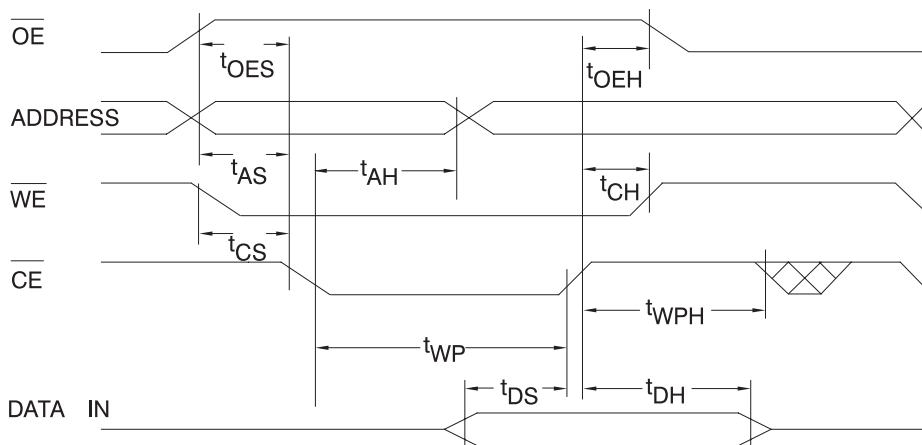
| Symbol             | Parameter                                                | Min | Max | Units |
|--------------------|----------------------------------------------------------|-----|-----|-------|
| $t_{AS}, t_{OES}$  | Address, $\overline{OE}$ Set-up Time                     | 0   |     | ns    |
| $t_{AH}$           | Address Hold Time                                        | 50  |     | ns    |
| $t_{CS}$           | Chip Select Set-up Time                                  | 0   |     | ns    |
| $t_{CH}$           | Chip Select Hold Time                                    | 0   |     | ns    |
| $t_{WP}$           | Write Pulse Width ( $\overline{WE}$ or $\overline{CE}$ ) | 90  |     | ns    |
| $t_{DS}$           | Data Set-up Time                                         | 35  |     | ns    |
| $t_{DH}, t_{OE H}$ | Data, $\overline{OE}$ Hold Time                          | 0   |     | ns    |
| $t_{WPH}$          | Write Pulse Width High                                   | 100 |     | ns    |

## 15. AC Byte Load Waveforms

### 15.1 $\overline{WE}$ Controlled



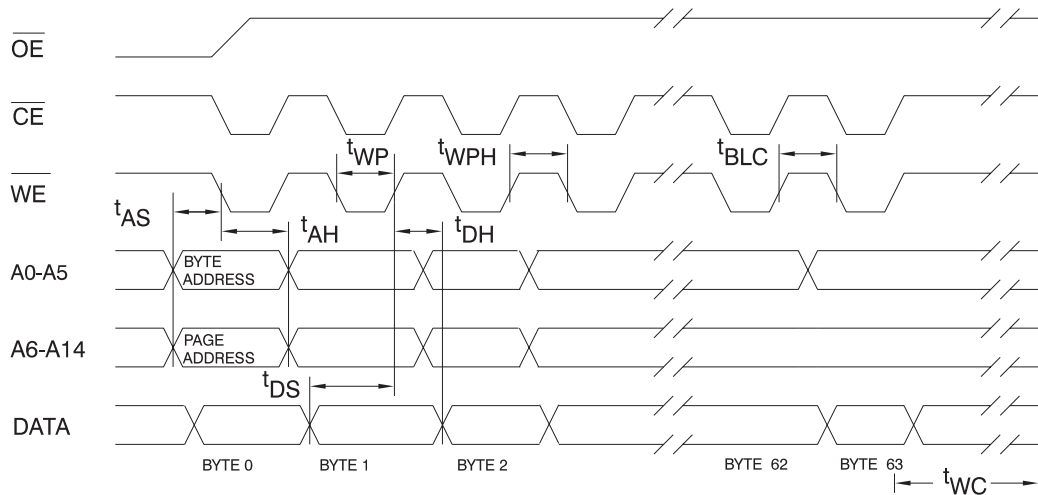
### 15.2 $\overline{CE}$ Controlled



## 16. Program Cycle Characteristics

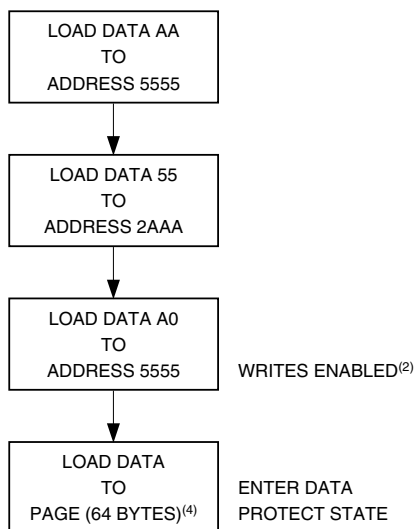
| Symbol    | Parameter              | Min | Max | Units   |
|-----------|------------------------|-----|-----|---------|
| $t_{WC}$  | Write Cycle Time       |     | 10  | ms      |
| $t_{AS}$  | Address Set-up Time    | 0   |     | ns      |
| $t_{AH}$  | Address Hold Time      | 50  |     | ns      |
| $t_{DS}$  | Data Set-up Time       | 35  |     | ns      |
| $t_{DH}$  | Data Hold Time         | 0   |     | ns      |
| $t_{WP}$  | Write Pulse Width      | 90  |     | ns      |
| $t_{BLC}$ | Byte Load Cycle Time   |     | 150 | $\mu$ s |
| $t_{WPH}$ | Write Pulse Width High | 100 |     | ns      |

## 17. Program Cycle Waveforms<sup>(1)(2)(3)</sup>



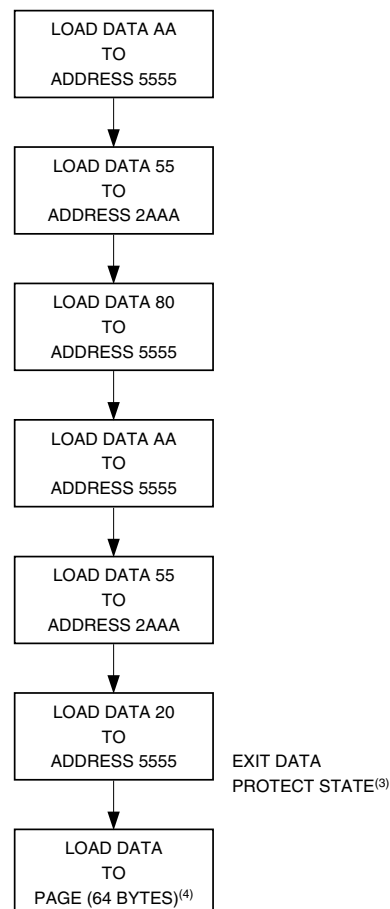
- Notes:
1. A6 through A14 must specify the page address during each high-to-low transition of  $\overline{WE}$  (or  $\overline{CE}$ ).
  2.  $\overline{OE}$  must be high when  $\overline{WE}$  and  $\overline{CE}$  are both low.
  3. All bytes that are not loaded within the page being programmed will be indeterminate.

## 18. Software Data Protection Enable Algorithm<sup>(1)</sup>

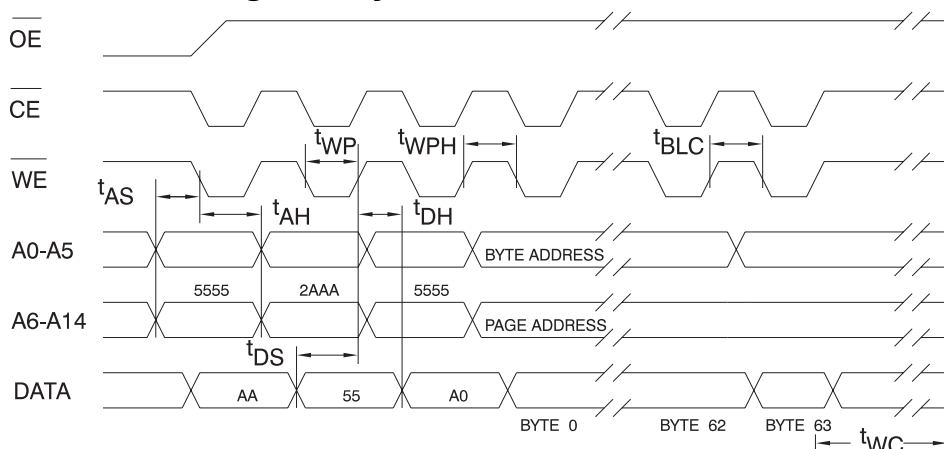


- Notes:
1. Data Format: I/O7 - I/O0 (Hex); Address Format: A14 - A0 (Hex).
  2. Data Protect state will be re-activated at end of program cycle.
  3. Data Protect state will be deactivated at end of program period.
  4. 64 bytes of data **MUST BE** loaded.

## 19. Software Data Protection Disable Algorithm<sup>(1)</sup>



## 20. Software Protected Program Cycle Waveform<sup>(1)(2)(3)</sup>



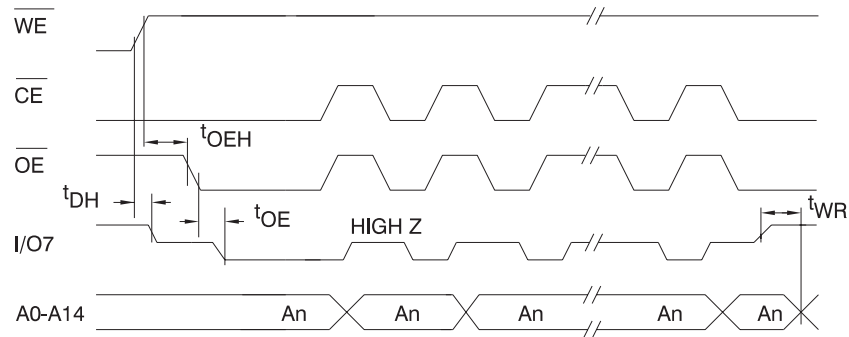
- Notes:
1. A6 through A14 must specify the page address during each high-to-low transition of  $\overline{WE}$  (or  $\overline{CE}$ ) after the software code has been entered.
  2.  $\overline{OE}$  must be high when  $\overline{WE}$  and  $\overline{CE}$  are both low.
  3. All bytes that are not loaded within the page being programmed will be indeterminate.

## 21. Data Polling Characteristics<sup>(1)</sup>

| Symbol               | Parameter                                      | Min | Typ | Max | Units |
|----------------------|------------------------------------------------|-----|-----|-----|-------|
| $t_{DH}$             | Data Hold Time                                 | 0   |     |     | ns    |
| $t_{OE\overline{H}}$ | $\overline{OE}$ Hold Time                      | 10  |     |     | ns    |
| $t_{OE}$             | $\overline{OE}$ to Output Delay <sup>(2)</sup> |     |     |     | ns    |
| $t_{WR}$             | Write Recovery Time                            | 0   |     |     | ns    |

Notes: 1. These parameters are characterized and not 100% tested.  
2. See  $t_{OE}$  spec in AC Read Characteristics.

## 22. Data Polling Waveforms

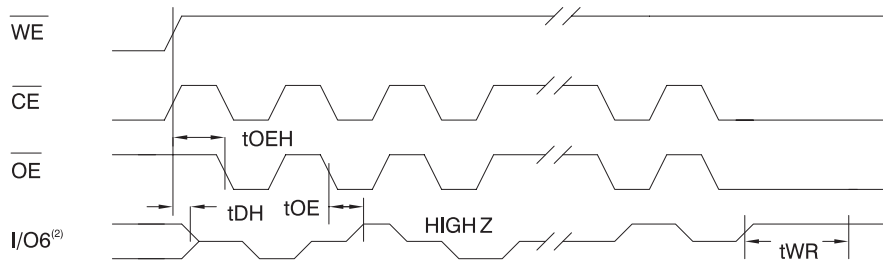


## 23. Toggle Bit Characteristics<sup>(1)</sup>

| Symbol               | Parameter                                      | Min | Typ | Max | Units |
|----------------------|------------------------------------------------|-----|-----|-----|-------|
| $t_{DH}$             | Data Hold Time                                 | 0   |     |     | ns    |
| $t_{OE\overline{H}}$ | $\overline{OE}$ Hold Time                      | 10  |     |     | ns    |
| $t_{OE}$             | $\overline{OE}$ to Output Delay <sup>(2)</sup> |     |     |     | ns    |
| $t_{OEHP}$           | $\overline{OE}$ High Pulse                     | 150 |     |     | ns    |
| $t_{WR}$             | Write Recovery Time                            | 0   |     |     | ns    |

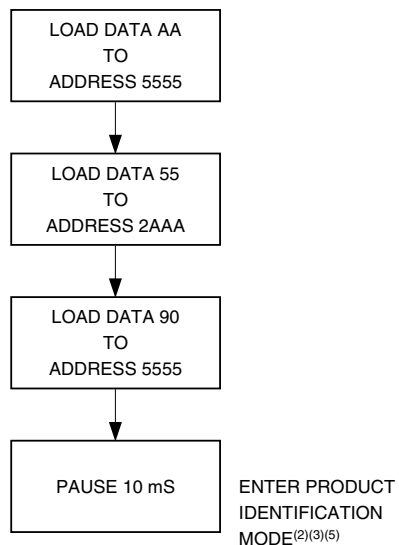
Notes: 1. These parameters are characterized and not 100% tested.  
2. See  $t_{OE}$  spec in AC Read Characteristics.

## 24. Toggle Bit Waveforms<sup>(1)(2)(3)</sup>

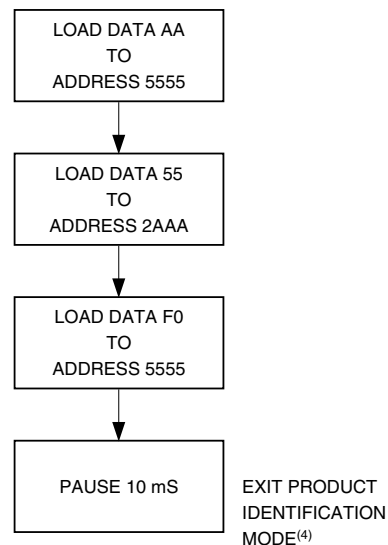


Notes: 1. Toggling either  $\overline{OE}$  or  $\overline{CE}$  or both  $\overline{OE}$  and  $\overline{CE}$  will operate toggle bit.  
2. Beginning and ending state of I/O6 will vary.  
3. Any address location may be used but the address should not vary.

## 25. Software Product Identification Entry<sup>(1)</sup>

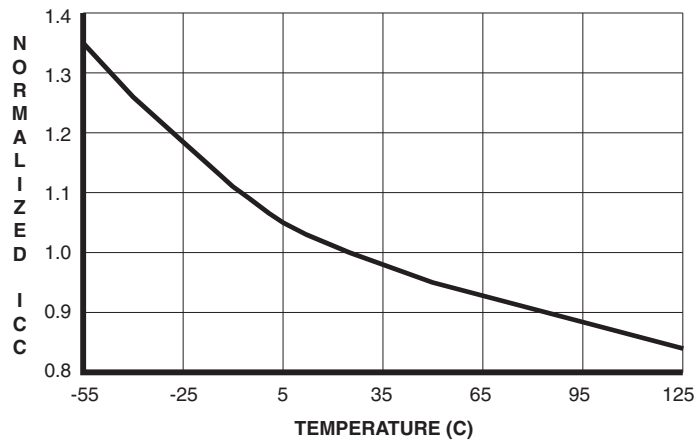


## 26. Software Product Identification Exit<sup>(1)</sup>

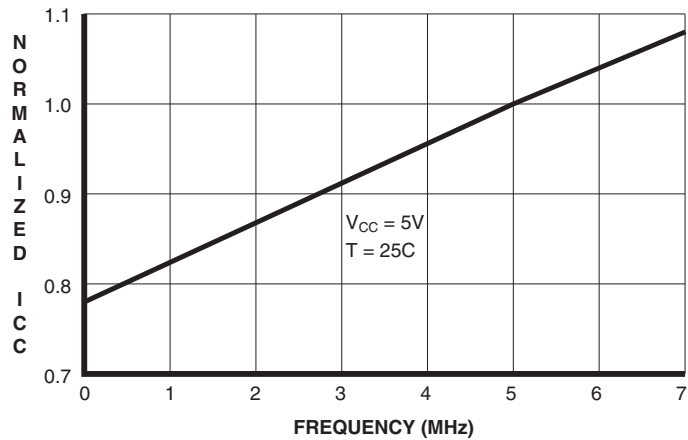


- Notes:
1. Data Format: I/O7 - I/O0 (Hex);  
Address Format: A14 - A0 (Hex).
  2. A1 - A14 =  $V_{IL}$ .  
Manufacturer Code is read for A0 =  $V_{IL}$ ;  
Device Code is read for A0 =  $V_{IH}$ .
  3. The device does not remain in identification mode if  
powered down.
  4. The device returns to standard operation mode.
  5. Manufacturer Code is 1F. The Device Code is DC.

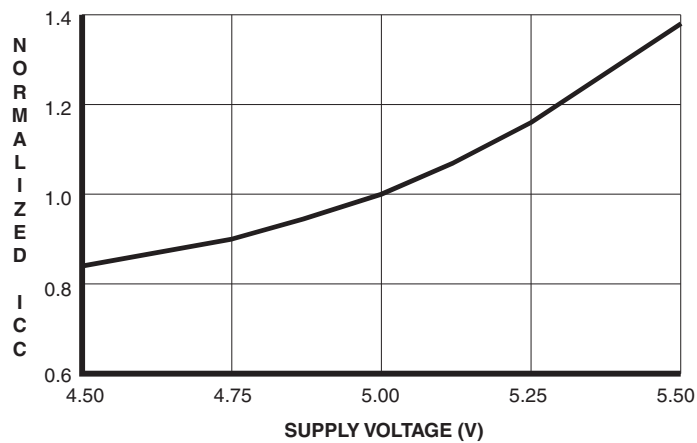
**NORMALIZED SUPPLY CURRENT  
vs. TEMPERATURE**



**NORMALIZED SUPPLY CURRENT  
vs. ADDRESS FREQUENCY**



**NORMALIZED SUPPLY CURRENT  
vs. SUPPLY VOLTAGE**



## 27. Ordering Information

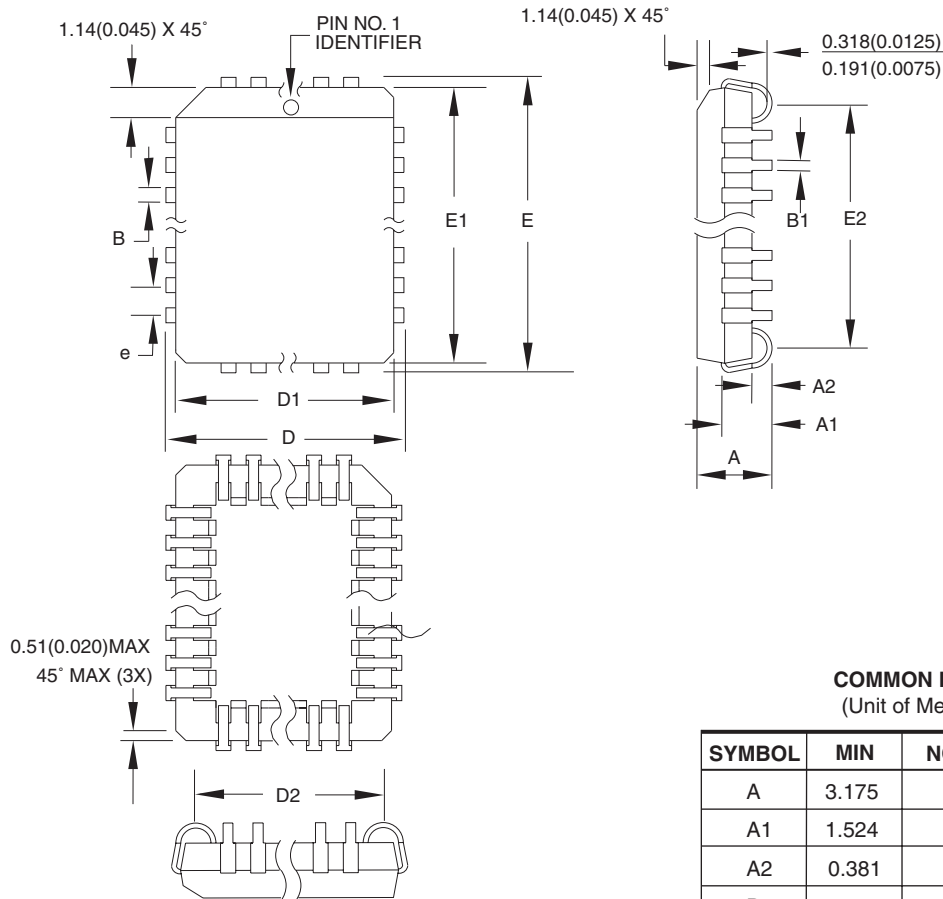
| t <sub>ACC</sub><br>(ns) | I <sub>CC</sub> (mA) |         | Ordering Code                  | Package    | Operation Range               |
|--------------------------|----------------------|---------|--------------------------------|------------|-------------------------------|
|                          | Active               | Standby |                                |            |                               |
| 70                       | 50                   | 0.3     | AT29C256-70JC<br>AT29C256-70TC | 32J<br>28T | Commercial<br>(0° to 70° C)   |
|                          |                      |         | AT29C256-70JI<br>AT29C256-70TI | 32J<br>28T | Industrial<br>(-40° to 85° C) |
| 90                       | 50                   | 0.3     | AT29C256-90JC<br>AT29C256-90TC | 32J<br>28T | Commercial<br>(0° to 70° C)   |
|                          |                      |         | AT29C256-90JI<br>AT29C256-90TI | 32J<br>28T | Industrial<br>(-40° to 85° C) |
| 120                      | 50                   | 0.3     | AT29C256-12JC<br>AT29C256-12TC | 32J<br>28T | Commercial<br>(0° to 70° C)   |
|                          |                      |         | AT29C256-12JI<br>AT29C256-12TI | 32J<br>28T | Industrial<br>(-40° to 85° C) |
| 150                      | 50                   | 0.3     | AT29C256-15JC<br>AT29C256-15TC | 32J<br>28T | Commercial<br>(0° to 70° C)   |
|                          |                      |         | AT29C256-15JI<br>AT29C256-15TI | 32J<br>28T | Industrial<br>(-40° to 85° C) |

Note:  Not recommended for New Designs.

| Package Type |                                                    |
|--------------|----------------------------------------------------|
| <b>32J</b>   | 32-lead, Plastic J-leaded Chip Carrier (PLCC)      |
| <b>28T</b>   | 28-lead, Plastic Thin Small Outline Package (TSOP) |

## 28. Packaging Information

### 28.1 32J – PLCC



**COMMON DIMENSIONS**  
(Unit of Measure = mm)

| SYMBOL | MIN       | NOM | MAX    | NOTE   |
|--------|-----------|-----|--------|--------|
| A      | 3.175     | –   | 3.556  |        |
| A1     | 1.524     | –   | 2.413  |        |
| A2     | 0.381     | –   | –      |        |
| D      | 12.319    | –   | 12.573 |        |
| D1     | 11.354    | –   | 11.506 | Note 2 |
| D2     | 9.906     | –   | 10.922 |        |
| E      | 14.859    | –   | 15.113 |        |
| E1     | 13.894    | –   | 14.046 | Note 2 |
| E2     | 12.471    | –   | 13.487 |        |
| B      | 0.660     | –   | 0.813  |        |
| B1     | 0.330     | –   | 0.533  |        |
| e      | 1.270 TYP |     |        |        |

- Notes:
1. This package conforms to JEDEC reference MS-016, Variation AE.
  2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010" (0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
  3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01



2325 Orchard Parkway  
San Jose, CA 95131

**TITLE**

**32J, 32-lead, Plastic J-leaded Chip Carrier (PLCC)**

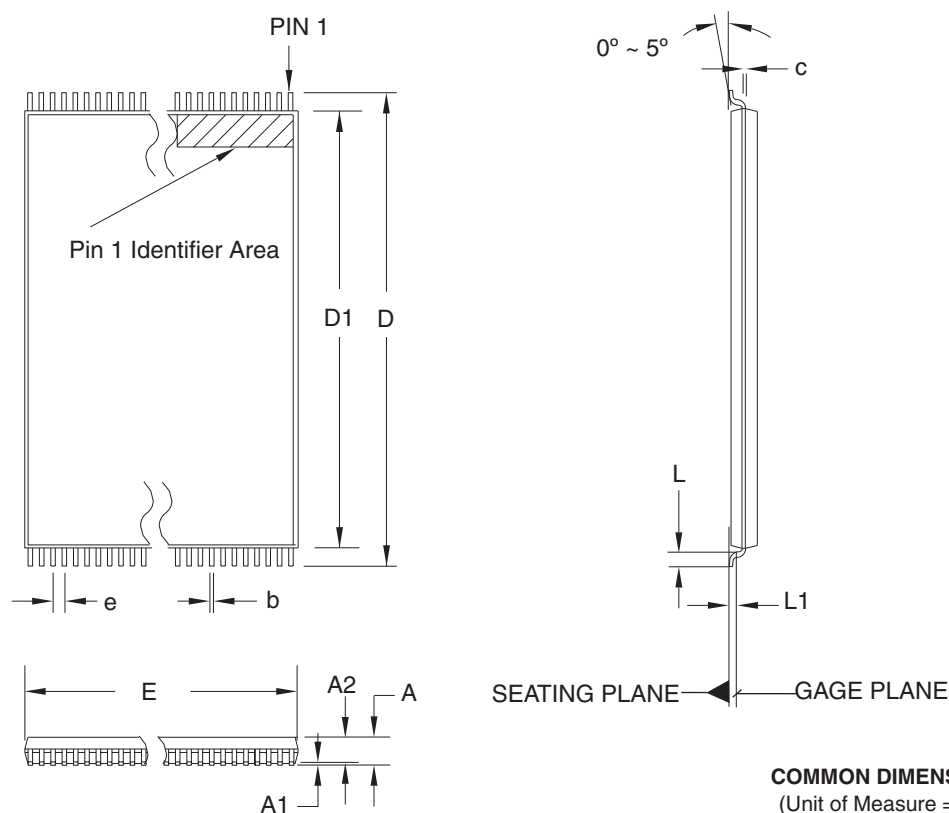
**DRAWING NO.**

32J

**REV.**

B

## 28.2 28T – TSOP



**COMMON DIMENSIONS**  
(Unit of Measure = mm)

| SYMBOL | MIN        | NOM   | MAX   | NOTE   |
|--------|------------|-------|-------|--------|
| A      | —          | —     | 1.20  |        |
| A1     | 0.05       | —     | 0.15  |        |
| A2     | 0.90       | 1.00  | 1.05  |        |
| D      | 13.20      | 13.40 | 13.60 |        |
| D1     | 11.70      | 11.80 | 11.90 | Note 2 |
| E      | 7.90       | 8.00  | 8.10  | Note 2 |
| L      | 0.50       | 0.60  | 0.70  |        |
| L1     | 0.25 BASIC |       |       |        |
| b      | 0.17       | 0.22  | 0.27  |        |
| c      | 0.10       | —     | 0.21  |        |
| e      | 0.55 BASIC |       |       |        |

- Notes:
1. This package conforms to JEDEC reference MO-183.
  2. Dimensions D1 and E do not include mold protrusion. Allowable protrusion on E is 0.15 mm per side and on D1 is 0.25 mm per side.
  3. Lead coplanarity is 0.10 mm maximum.

12/06/02



2325 Orchard Parkway  
San Jose, CA 95131

**TITLE**

**28T**, 28-lead (8 x 13.4 mm) Plastic Thin Small Outline  
Package, Type I (TSOP)

**DRAWING NO.**

28T

**REV.**

C



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